

**What is claimed is:**

1    1.     A device comprising:  
2           a tip of a bonding tool having a dissipative material for use in wire bonding  
3    machines for connecting leads to integrated circuit bonding pads, wherein the tip has a  
4    static discharge time between 0.1 and 0.5 seconds.

1    2.     A device comprising:  
2           a bonding tool tip having an electrically dissipative ceramic for use in capillary  
3    wedge-type wire bonding machines for connecting leads to integrated circuit bonding  
4    pads.

1    3.     A method of using a bonding tool tip, comprising:  
2           providing an electrically dissipative bonding tool tip;  
3           bonding a material to a device;  
4           allowing an essentially smooth current to dissipate to the device, the current  
5    being low enough so as not to damage said device being bonded and  
6    high enough to avoid a build up of charge that could discharge to the device being  
7    bonded and damage the device being bonded.